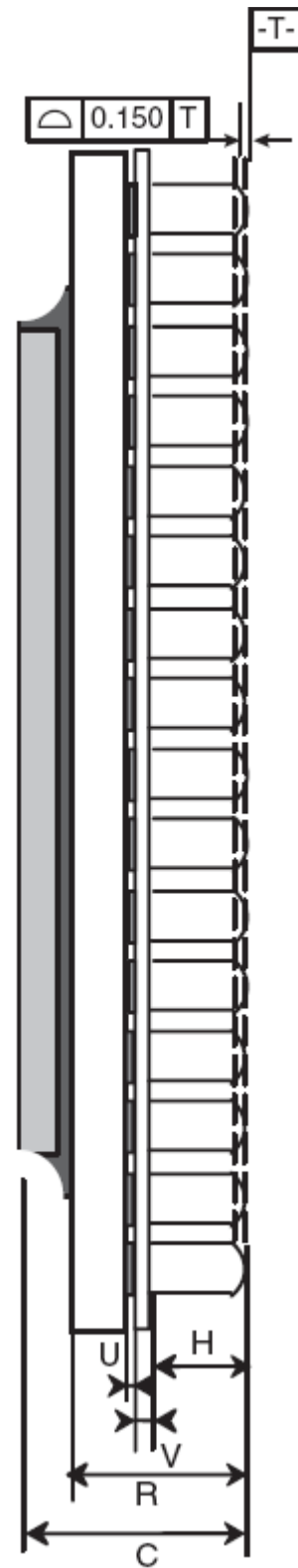
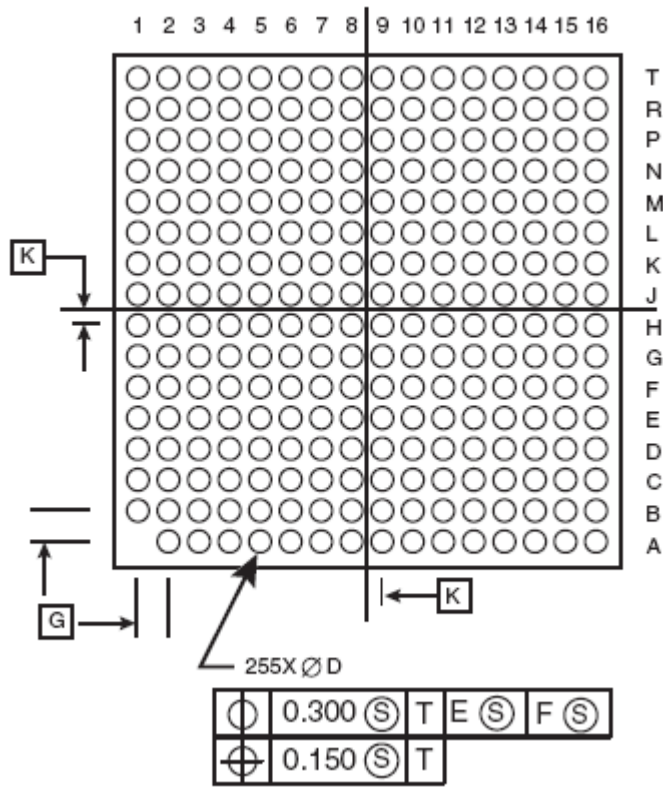
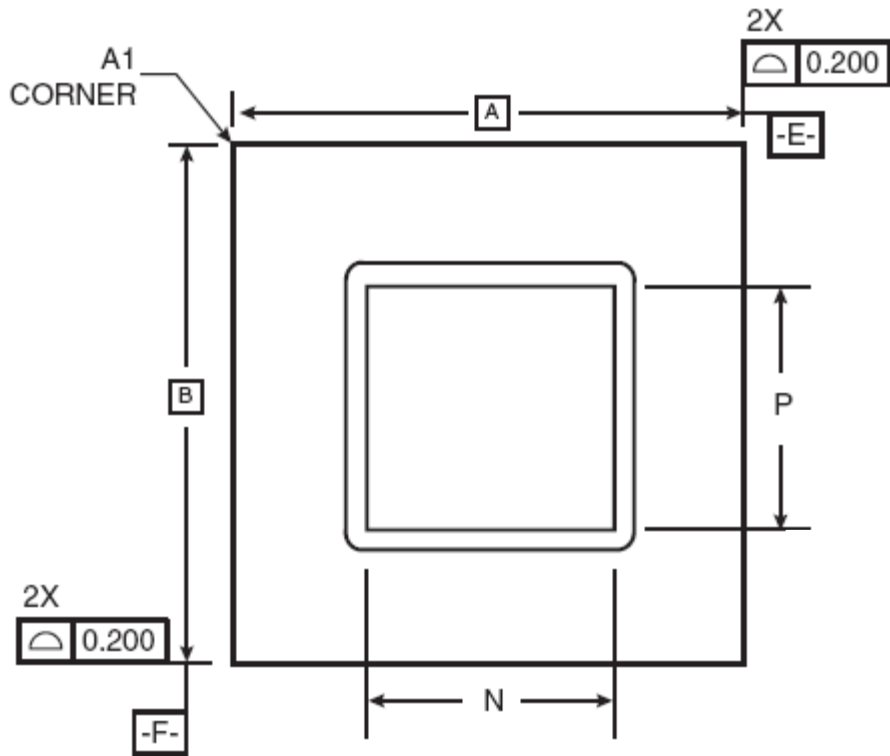


### 15.3 CI-CGA Package Parameters

The package parameters are as provided in the following list. The package type is 21 mm, 255-lead ceramic ball grid array (CI-CGA).

Package outline	21 mm × 21 mm
Interconnects	255
Pitch	1.27 mm
Typical module height	3.84 mm



Notes: 1. Dimensioning and tolerancing per ASME Y14.5M—1994  
2. Controlling dimension: millimeter

Dim	Millimeters	
	Min	Max
A	21.000 BSC	
B	21.000 BSC	
C	3.84 BSC	
D	0.790	0.990
G	1.270 BSC	
H	1.545	1.695
K	0.635 BSC	
N	5.000	
P	7.000	
R	3.02 BSC	
U	0.10 BSC	
V	0.25	0.35